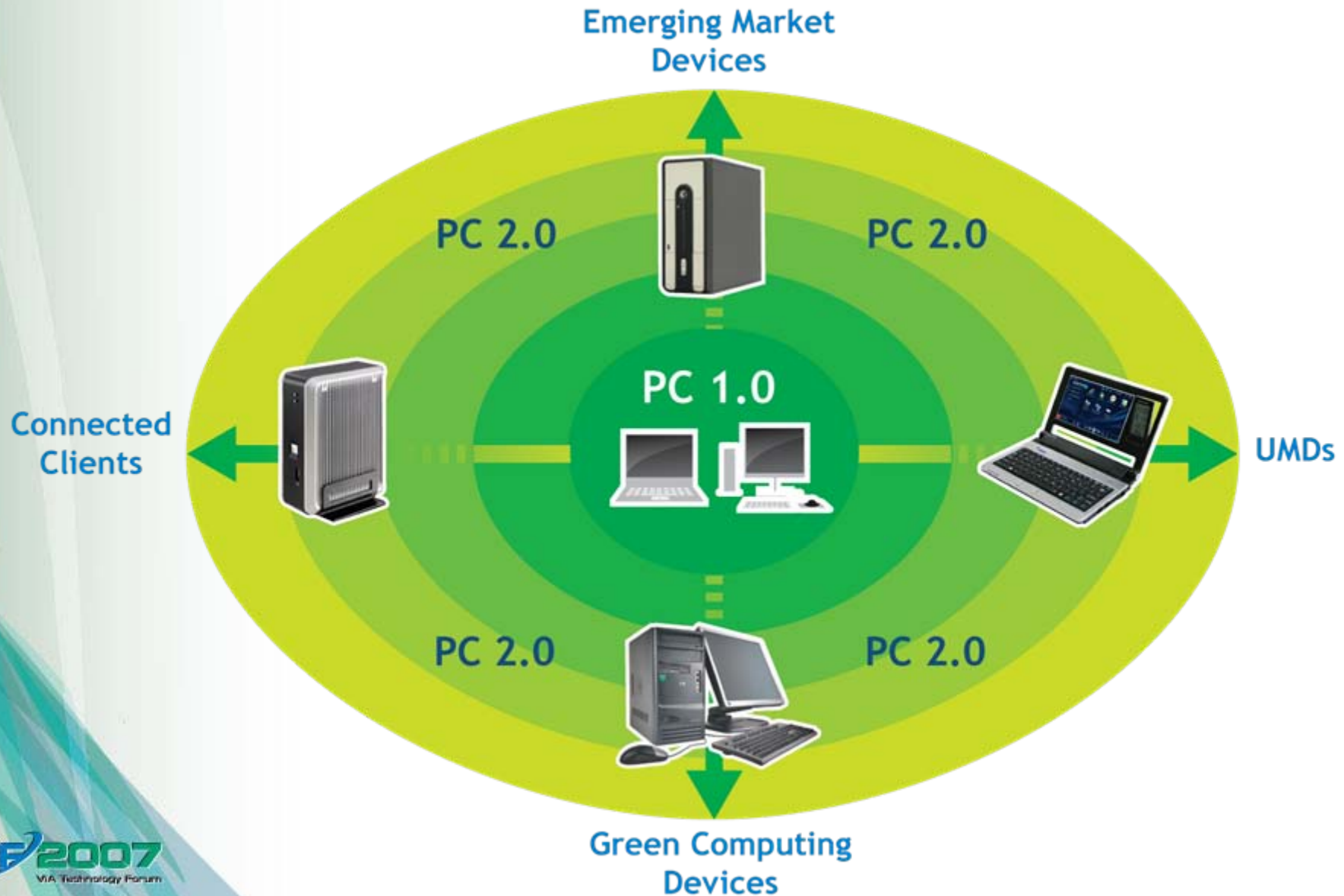




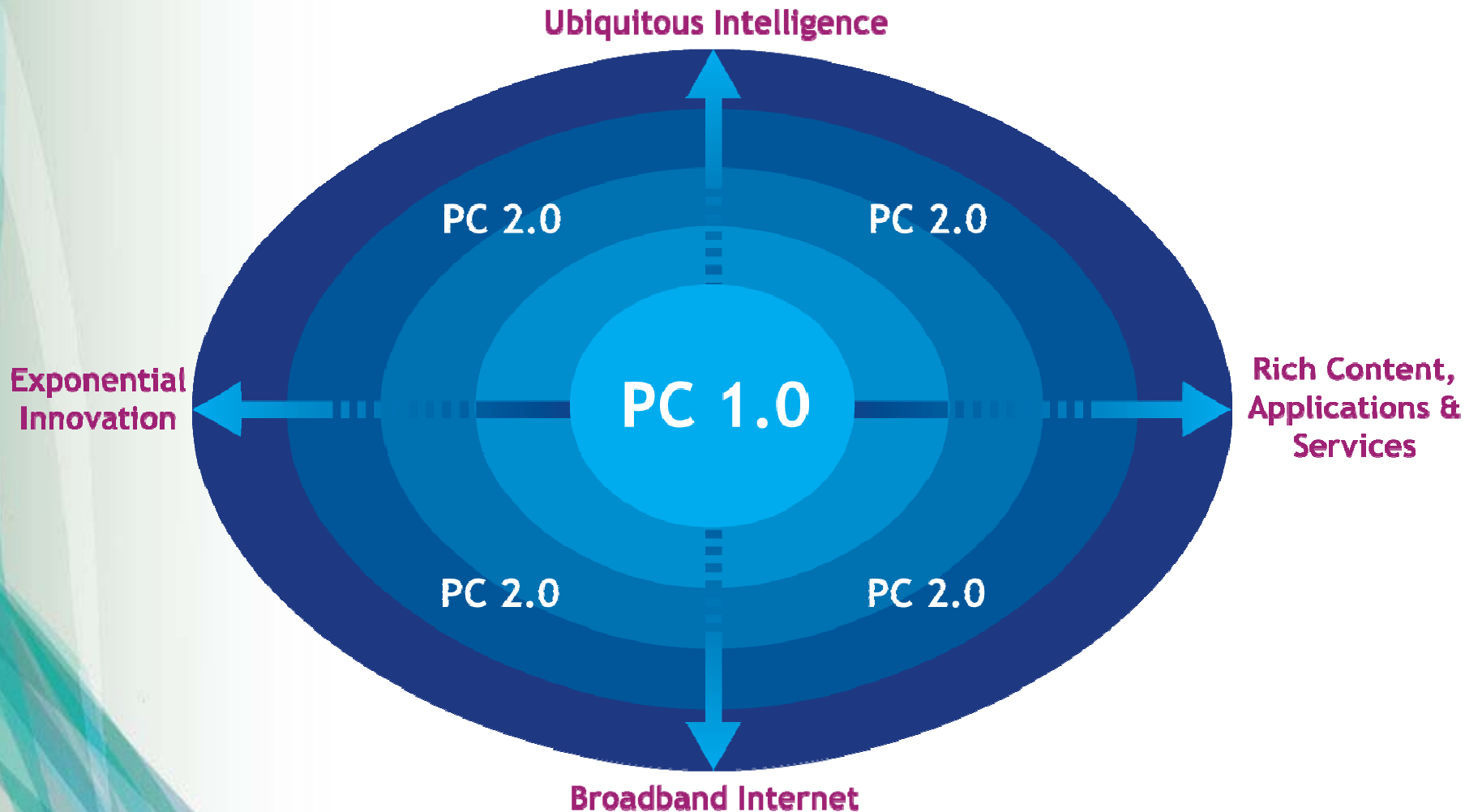
Leading the Transition to PC 2.0

Wenchi Chen
President & CEO
VIA Technologies, Inc

PC 2.0: Ubiquitous Intelligence



PC 2.0 Drivers



Partnering for PC 2.0

- Silicon Platform Providers
- Device Manufacturers
- Software Application Developers
- Content Providers
- Broadband Service Providers



中華電信

Strategic Alliance to Deliver 3.5G Services for UMDs

Shiao-Tung Chang
Senior Vice President
Chunghwa Telecom

PC 2.0 Platform Requirements

- Miniaturization
- Low Power Consumption
- Complete x86 and Internet Compatibility
- Rich Digital Media Performance
- Flexible Broadband Connectivity
- Affordability

VIA: Driving the Transition to PC 2.0



“Small is Beautiful”

- Smallest Footprint x86 Processor Platform
 - 40% Smaller than Competitor Offerings
 - Enables Lightest, Sleekest, & Most Stylish Form Factors
- Most Energy Efficient x86 Processor Platform
 - Lowest TDP x86 Platform
 - Best Performance Per Watt
 - Longest Battery Life
 - Coolest and Quietest Operation
- Most Highly-Integrated Feature-Rich x86 Processor Platform
 - Seamless Multimedia Experience
 - Enhanced Computing Performance
 - Multiple Connectivity Options

VIA Processor Platforms

Playing by Traditional Industry Rules

- Socket Compatibility
 - MHz Madness
- Price/Performance



Mini-ITX

Setting New Industry Standards

- Platform Integration
 - Form Factor Miniaturization
- Power Consumption
- New Market Innovation

2000

2002

2007

Shrinking the Form Factor

Silicon Level



Socket 370
50x50mm

- 51%



EBGA
35x35mm

- 64%



NanoBGA2
21x21mm

Platform Level



Mini-ITX
17cmx17cm

- 50%



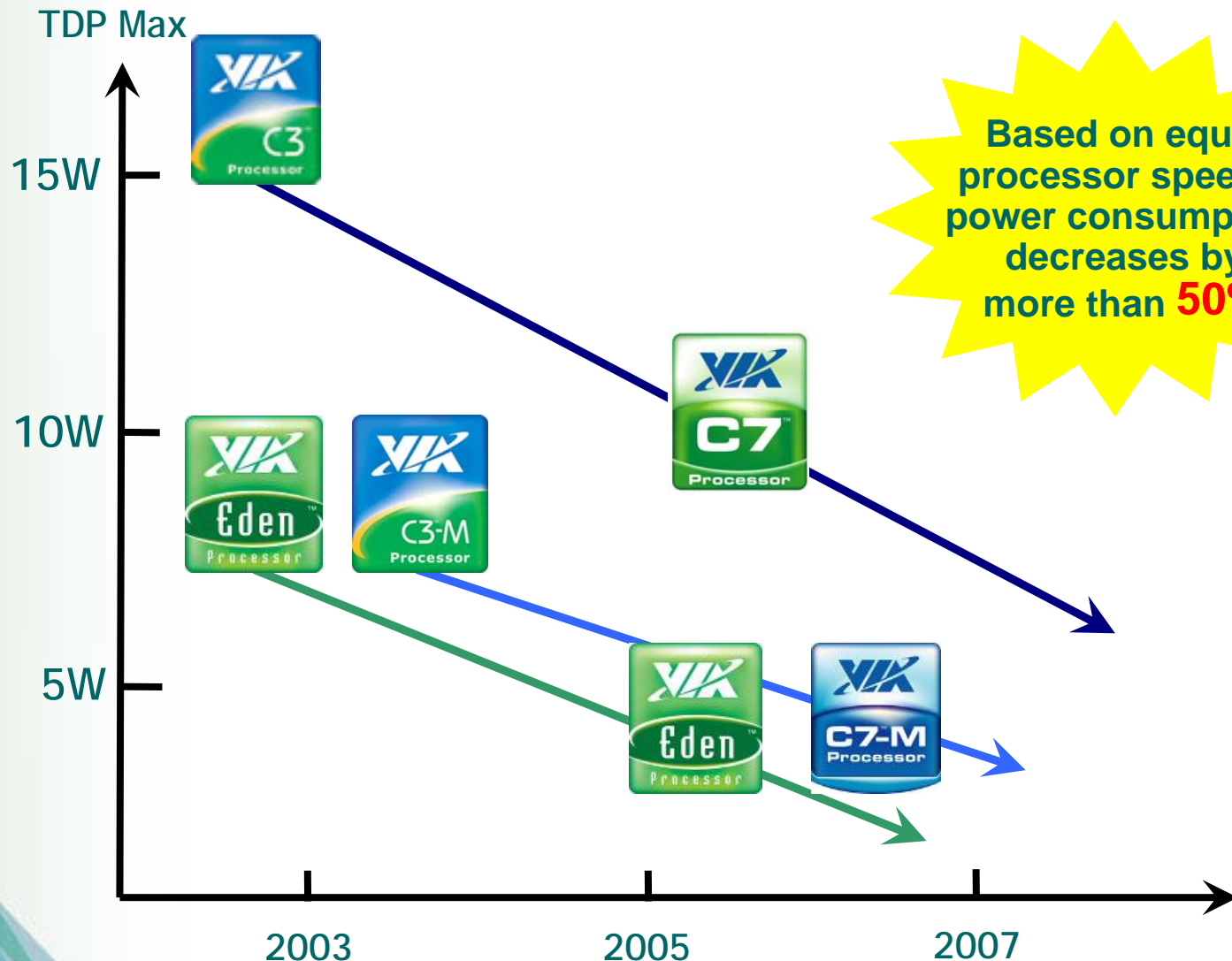
Nano-ITX
12cmx12cm

- 50%



Pico-ITX
10cmx7.2cm

Reducing the Power



Leading Green Computing Innovation

HP Compaq dx2020 Energy Efficient Desktop PC for China



Processor:	1.5GHz VIA C7-D
Memory	256MB ~ 1GB DDR2 533 SDRAM
HDD:	80GB or 160GB SATA
Dimension:	36.7 x 17.5 x 42.0 cm
Optical:	52X CD-ROM & 16X/48X DVD-ROM
Graphics:	VIA UniChrome Pro IGP
Peripherals:	6x USB2.0 ports
OS:	Microsoft® Windows® XP

Leading Connected Client Innovation

Almost 50% of all thin clients sold in 2005 were powered by VIA processors.



---- IDC October 2006 (Connected Clients: The New Enterprise Reality)



CITRIX®

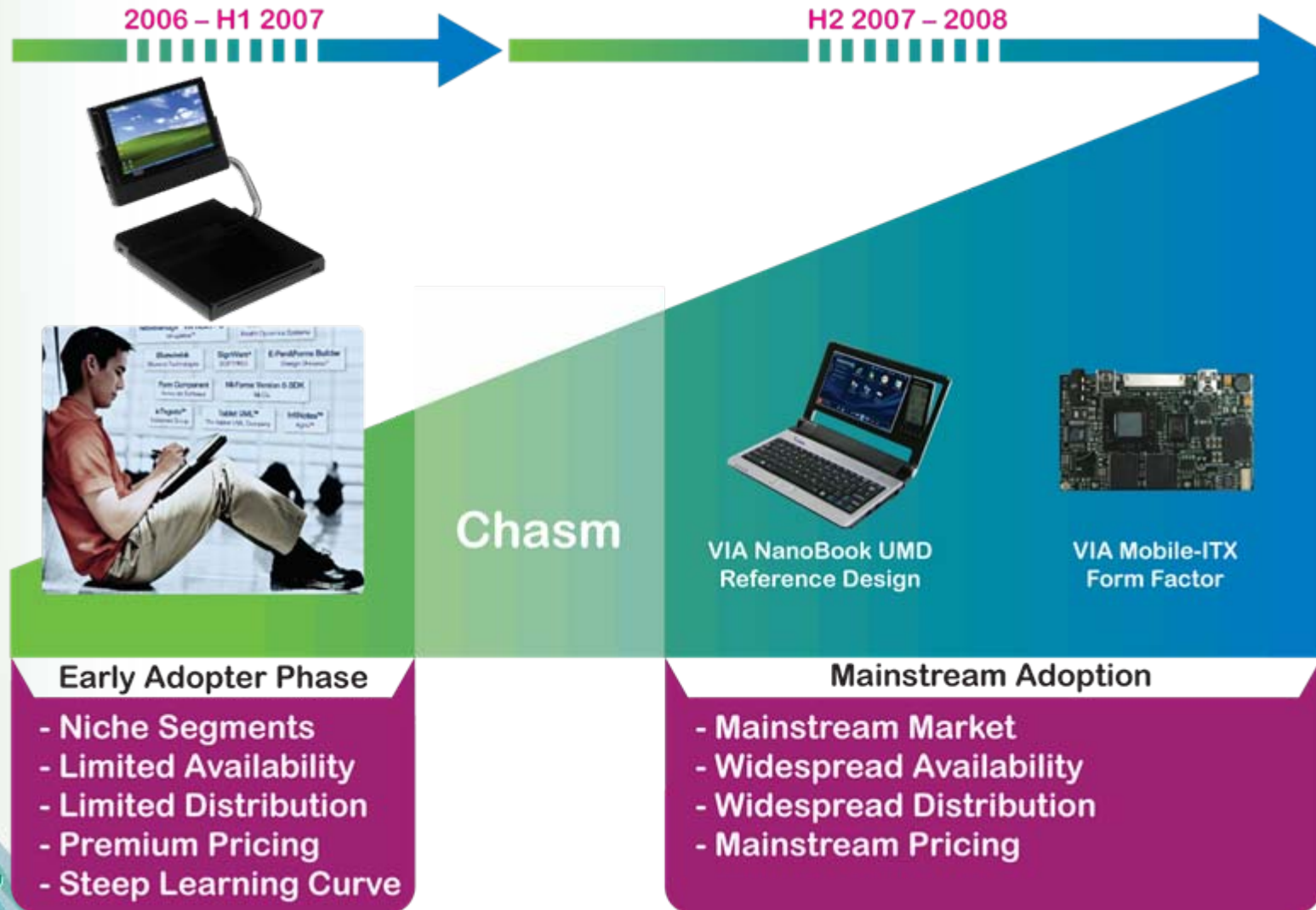


Leading UMD Innovation

VIA leads the industry with the largest number of UMD design wins in the market today!



Bringing UMDs into the Mainstream



VIA NanoBook UMD Reference Design



nano
Book

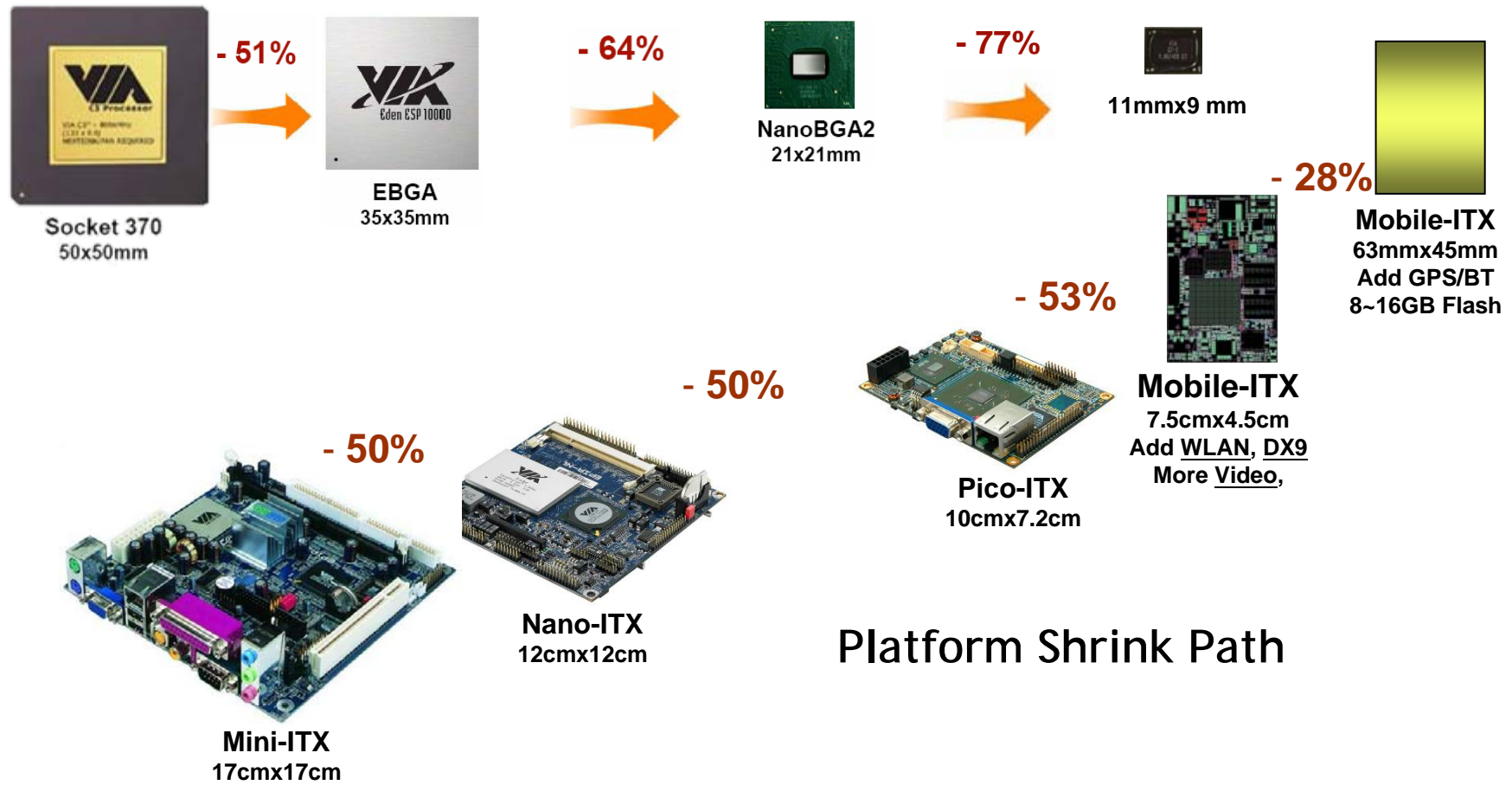
VIA Mobile-ITX



*World's First Industry Standard
Form Factor for PC/Phone
Convergence*

Miniaturizing to the Max!

CPU Shrink Path



Platform Shrink Path

2002

2005

2007

2009

VIA: Leading the Transition to PC 2.0

- Smallest footprint, lowest power, and most feature rich x86 platforms for driving ubiquitous intelligence
- Industry leadership in miniaturization to enable new form factors, device categories, and usage models
- Opening up exciting new opportunities for innovation and true product differentiation

VTF2007 Industry Support



AWIND Inc. | CHIMEI Optoelectronics Corporation (CMO)

Danoo, Inc. | GTNT H.K. Limited | IDC, Taiwan

Microsoft | Packard Bell | Stonewall Networks, Inc.

Research, Development and Evaluation Commission (RDEC)

Wyse Technology Inc. | Zonbu

VTF2007 Agenda

Time	Enabling Ultra Mobility Technology Track	Time	Connected Client Computing Technology Track
14:00 – 14:10	Opening	14:00 - 14:10	Opening
14:10 – 14:35	VIA Ultra Mobility Platforms Epan Wu VIA Technologies, Inc.	14:10 - 14:35	The Virtualization of the Client and the Disruption That Ensues Jay Yang IDC
14:35 – 15:00	Securing A Mobile Enterprise James Hinderliter Stonewall Networks, Inc.	14:35 - 15:00	Connected Experience Rex Wei Microsoft Corporation
15:00 – 15:25	GTNT Mobile Service Dr. Allan Yang GTNT HK Limited	15:00 - 15:25	Wyse Thin Client Computing Patrick Wang Wyse Technology Inc.
15:25 – 15:40	Coffee Break	15:25 - 15:50	VIA Connected Client Platforms Epan Wu VIA Technologies, Inc.
15:40 – 16:05	Enabling Ultra Mobility Technology - The Government Perspective Chuan-te Ho REDC	15:50 - 16:05	Coffee Break
16:05 – 16:30	"Mobile" to "Ultra Mobile": CMO's Perspective of UMPC New Revolution James Yang CHIMEI Optoelectronics Corporation	16:05 - 16:30	A brave New World of Consumer Experience Dr. Mike Yang Danoo Inc.
		16:30 - 16:55	Hassle-free \$99 green computer Gregoire Gentil Zonbu
		16:55 – 17:20	Mobility in Business Kuo-Lung Chang AWIND Inc.

Thank You!